



Ultra High Thermal Application

Parameter	Test/Measure	DN-1206QB	DN-1206CR1	DN-1208R1	DN-1301B	DN-1301C
Curing Temp	degC	200	200	200	175	175
Viscosity @25deg.C	E-viscometer@5rpm	11,000	10,800	12,000	13,000	10,800
Thixotropic Index @25deg.C	0.5rpm/5rpm	5.5	6.1	3.0	5.5	6.1
Open Time (for 1*1 mm2 die size)	Hour	6	4	6	6	4
Volume Resistance	Ohm.cm	5.5×10^{-6}	9.0×10^{-6}	3.9×10^{-6}	2.5×10^{-6}	9.0×10^{-6}
Thermal Conductivity	W/mk	140	150	230	130	130
Die Shear Strength @25 Deg.C with 2*2 mm Ag BSM Die	On Ag/Cu LF (Mpa)	35	32	100	32	32
	On Cu PCB (Mpa)	15	32	12	25	27
Die Shear Strength @260 Deg.C 2*2 mm Ag BSM Die	On Ag/Cu LF (Mpa)	15	17	100	19	16
	On Cu PCB (Mpa)	10	10	12	12	10
Storage Modulus@25 Deg.C	GPa	15.1	13	18	18	13
CTE	ppm	40	30	15.2	51	30
Product Benefit		1.Good Reliability 2.Long open time	1.For printing & dispensing 2.Chemical resistance	1.Extreme high TC 2.Great adhesion on Ag & Au finish	1.Good workability 2.Long open time 3.Less CTE mismatch	1.Good RBO 2.Die size up to 5*5 3.Good adhesion on Cu